CFD4448

SURFACE MOUNT ULTRA HIGH SPEED SILICON SWITCHING DIODE





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DESCRIPTION:

The CENTRAL SEMICONDUCTOR CFD4448 is an ultra high speed switching diode ideal for applications where very small size and operational efficiency are prime requirements.

MARKING CODE: X

APPLICATIONS:

- General Purpose Switching
- DC DC Converters
- Flyback Diodes
- Polarity Protection
- Battery powered applications including Cell Phones, Digital Cameras, Pagers, PDAs, Laptop Computers, etc.

FEATURES:

- Current (I_O=250mA)
- Forward Voltage Drop (V_F=0.91V TYP @ 100mA)
- Extremely Fast Switching Speed (4ns Max)
- Small TLP, 1.0 x 0.6 x 0.4mm, Ultra Low Profile Leadless Surface Mount Package.

MAXIMUM RATINGS: (T _A =25°C)	SYMBOL		UNITS
Peak Repetitive Reverse Voltage	V_{RRM}	120	V
Continuous Forward Current	Ιϝ	250	mA
Peak Repetitive Forward Current	IFRM	500	mA
Peak Forward Surge Current, tp=1.0µs	^I FSM	4.0	Α
Peak Forward Surge Current, tp=1.0s	^I FSM	1.0	Α
Power Dissipation	P_{D}	100	mW
Operating and Storage Junction Temperature	T _J , T _{stg}	-65 to +175	°C
Thermal Resistance	ΘιΛ	1500	°C/W

ELECTRICAL CHARACTERISTICS: (T_A=25°C unless otherwise noted)

SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNITS
I_{R}	V _R =50V			300	nA
I_{R}	V _R =50V, T _A =125°C			100	μΑ
I_{R}	V _R =100V			500	nA
BV_R	I _R =100μA	120	150		V
V_{F}	I _F =1.0mA	0.55	0.59	0.65	V
V_{F}	I _F =10mA	0.67	0.72	0.77	V
V_{F}	I _F =100mA	0.85	0.91	1.0	V
C_T	$V_R=0$, f=1.0MHz			2.0	pF
t _{rr}	$I_R = I_F = 10$ mA, $I_{rr} = 1.0$ mA, $R_L = 100$ Ω		2.0	4.0	ns

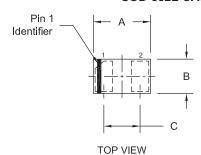
R3 (28-September 2011)

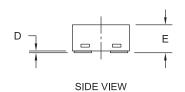
CFD4448

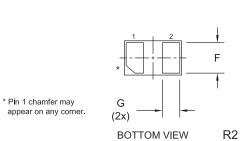
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SOD-882L CASE - MECHANICAL OUTLINE







DIMENSIONS						
	INCHES		MILLIMETERS			
SYMBOL	MIN	MAX	MIN	MAX		
Α	0.037	0.041	0.95	1.05		
В	0.022	0.026	0.55	0.65		
С	0.026		0.65			
D	0.000	0.002	0.00	0.05		
E	0.012	0.016	0.30	0.40		
F	0.018	0.022	0.45	0.55		
G	0.008	0.012	0.20	0.30		

SOD-882L (REV:R2)

LEAD CODE:

- 1) Cathode 2) Anode

MARKING CODE: X

OUTSTANDING SUPPORT AND SUPERIOR SERVICES



PRODUCT SUPPORT

Central's operations team provides the highest level of support to insure product is delivered on-time.

- Supply management (Customer portals)
- · Inventory bonding
- · Consolidated shipping options

- · Custom bar coding for shipments
- · Custom product packing

DESIGNER SUPPORT/SERVICES

Central's applications engineering team is ready to discuss your design challenges. Just ask.

- Free guick ship samples (2nd day air)
- Online technical data and parametric search
- SPICE models
- · Custom electrical curves
- · Environmental regulation compliance
- · Customer specific screening
- · Up-screening capabilities

- Special wafer diffusions
- PbSn plating options
- Package details
- Application notes
- · Application and design sample kits
- · Custom product and package development

REQUESTING PRODUCT PLATING

- 1. If requesting Tin/Lead plated devices, add the suffix "TIN/LEAD" to the part number when ordering (example: 2N2222A TIN/LEAD).
- 2. If requesting Lead (Pb) Free plated devices, add the suffix "PBFREE" to the part number when ordering (example: 2N2222A PBFREE).

CONTACT US

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